

Patent

Customer No.: 31561
Application No.: 10/604,409
Docket No. 10672-US-PA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Lee et al.
Application No. : 10/604,409
Filed : 2003/07/18
For : STACK CHIP PACKAGE STRUCTURE
Art Unit : 2814
Examiner : HIA, NATHAN W

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(Via fax: 4 pages, followed by confirmation copy via courier)

ASSISTANT COMMISSIONER FOR PATENTS
Arlington, VA22202

Dear Sirs,

In response to the Advisory Action dated July 07, 2004, please find the relevant paper in response to paper No. 20040604. Following the fax transmission, a hard copy via courier will also be forwarded to the Office.

Enclosed please find:

- ☒ Request for Continued Examination in (2) pages
- ☒ Fax confirmation report
- ☒ Prepaid return postcard

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

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Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date:

July 14, 2004

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